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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No.	Country Code - Document Number - Kind Code	Publication Date MM-DD-YYYY	Name of Patentee or Applicant	Trans.
/EW/	AA	JP 2002-508452	03-19-2002		includes English language abstract
	AB	JP 2002-506927	03-05-2002		includes English language abstract
	AC	JP 63-310989	12-19-1988	Shimamura, et al.	includes English language abstract
	AD	JP 2004-137588	05-13-2004	Kumagai, et al.	includes English language abstract
	AE	JP 08-156176	06-18-1996	Kataoka, et al.	includes English language abstract
	AF	JP 2000-261113	09-22-2000	Yamamori, et al.	includes English language abstract

NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No.	(Include Author, Title, Date, Pages, Etc.)
/EW/	AG	Japanese language Office Action in a counterpart foreign application dated July 6, 2009 (4 sheets)
	AH	Japanese language Office Action in a counterpart foreign application dated May 8, 2009 (4 sheets)
	AI	Japanese language Office Action in a counterpart foreign application dated April 9, 2009 (3 sheets)
	AJ	"Voltammetric and morphological characterization of copper electrodeposition from non-cyanide electrolyte", M.R.H. DE ALMEIDA, et al., Journal of Applied Electrochemistry, Vol. 32, pp. 763-773 (2002)

EXAMINER SIGNATURE	/Edna Wong/	DATE CONSIDERED	04/01/2010
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.